What is claimed is:

1. An arrangement, comprising:

an integrated circuit, having a housing with a plurality of connector pins;

a printed circuit board having conducting paths, to which the integrated circuit is electrically and mechanically contacted by connector pins; and

at least one blocking capacitor, which is switched into a power supply path for the integrated circuit, wherein

the blocking capacitor, of which there is at least one, is spatially arranged between the connector pins of the housing and is electrically contacted to the connector pins.

2. The arrangement according to claim 1, wherein the integrated circuit has a ball grid array housing with ball-shaped connector pins.

3. The arrangement according to claim 1, wherein the integrated circuit with the housing, the connector pins of which are inserted through openings of a carrier arranged between the housing and the printed circuit board.

4. The arrangement according to claim 3, wherein the openings are in the form of bore holes.

5. The arrangement according to claim 3, wherein the blocking capacitor, of which there is at least one, is positioned on a side of the carrier facing away from the housing.

6. The arrangement according to claim 3, wherein the blocking capacitor, of which there is at least one, is positioned on a side of the carrier facing toward the housing.

7. A carrier, comprising:

openings, through which connector pins of a housing surrounding an integrated circuit can be inserted; and

at least one blocking capacitor, which is mounted on the carrier between the openings.

8. A carrier, comprising:

openings, through which connector pins of a housing surrounding an integrated circuit can be inserted; and

at least one blocking capacitor, which is inserted into the carrier between the openings, such that the blocking capacitor is centrally positioned compared to the carrier sides.

9. The carrier according to claim 7, wherein the openings are in the form of bore holes.

10. The carrier according to claim 7, wherein the blocking capacitors are bonded onto the carrier.

11. The carrier according to claim 7, wherein the carrier is made out of a heat-resistant foil.

12. The arrangement according to claim 1, wherein a carrier comprising openings, through which connector pins of a housing surrounding an integrated circuit can be inserted, and at least one blocking capacitor, which is

mounted on the carrier between the openings, is introduced between the housing and printed circuit board.

13. A method for assembling at least one blocking capacitor, comprising:

arranging the at least one blocking capacitor in a current supply path for an integrated circuit, having a housing with a plurality of connector pins, which are electrically and mechanically contacted to conducting paths of a printed circuit board arranged in proximity to the housing; and

spatially arranging the at least one blocking capacitor between the printed circuit board and the integrated circuit and is contacted to the connector pins of the housing of the integrated circuit.

14. The method according to claim 13, wherein the blocking capacitor, of which there is at least one, is assembled before assembly onto or into a carrier between openings thereof.

15. The method according to claim 14, wherein the connector pins are inserted through the openings of the carrier positioned between the housing and the printed circuit board.

16. The carrier according to claim 8, wherein the openings are in the form of bore holes.

17. The carrier according to claim 8, wherein the blocking capacitors are bonded onto the carrier.

18. The carrier according to claim 8, wherein the carrier is made out of a heat-resistant foil.

19. The arrangement according to claim 1, wherein a carrier comprising openings, through which connector pins of a housing surrounding an integrated circuit can be inserted, and at least one blocking capacitor, which is inserted into the carrier between the openings, such that the blocking capacitor is centrally positioned compared to the carrier sides, is introduced between the housing and printed circuit board.